

Title (en)
NON-AMINE POST-CMP COMPOSITION AND METHOD OF USE

Title (de)
AMINFREIE POST-KMP-ZUSAMMENSETZUNG UND ANWENDUNGSVERFAHREN DAFÜR

Title (fr)
COMPOSITION APRÈS CMP SANS AMINES, AINSI QUE SON PROCÉDÉ D'UTILISATION

Publication
EP 2768920 A4 20150603 (EN)

Application
EP 11874382 A 20111021

Priority
US 2011057287 W 20111021

Abstract (en)
[origin: WO2013058770A1] A cleaning composition and process for cleaning post-chemical mechanical polishing (CMP) residue and contaminants from a microelectronic device having said residue and contaminants thereon. The cleaning compositions are substantially devoid of amine and ammonium-containing compounds, e.g., quaternary ammonium bases. The composition achieves highly efficacious cleaning of the post-CMP residue and contaminant material from the surface of the microelectronic device without compromising the low-k dielectric material or the copper interconnect material.

IPC 8 full level
H01L 21/02 (2006.01); **C11D 3/04** (2006.01); **C11D 3/43** (2006.01); **C11D 7/06** (2006.01); **C11D 7/50** (2006.01); **C11D 3/20** (2006.01); **C11D 3/34** (2006.01); **C11D 7/26** (2006.01); **C11D 7/34** (2006.01)

CPC (source: CN EP)
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Citation (search report)
• [XY] WO 2007047365 A2 20070426 - ADVANCED TECH MATERIALS [US], et al
• [X] US 2005245411 A1 20051103 - YANG BO [US], et al
• [Y] WO 2008039730 A1 20080403 - ADVANCED TECH MATERIALS [US], et al
• See references of WO 2013058770A1

Designated contracting state (EPC)
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DOCDB simple family (publication)
WO 2013058770 A1 20130425; CN 103958640 A 20140730; CN 103958640 B 20160518; CN 105869997 A 20160817; EP 2768920 A1 20140827; EP 2768920 A4 20150603; KR 101914817 B1 20181228; KR 20140082816 A 20140702

DOCDB simple family (application)
US 2011057287 W 20111021; CN 201180075099 A 20111021; CN 201610274374 A 20111021; EP 11874382 A 20111021; KR 20147013154 A 20111021